



BOW ELECTRONIC SOLDERS

BLF 227 LEAD-FREE ALLOY Technical Data Sheet

DESCRIPTION

Bow Electronic Solders has developed BLF 227, a low-cost Lead-Free solder. BLF 227 is a near eutectic Tin/Copper/Nickel alloy. This alloy is proven to perform well in surface mount, wave soldering, and hand soldering applications. BLF 227 alloy may be used with existing equipment, processes, coatings, and flux chemistries. BLF 227 compares favorably to other low-cost, lead-free alloys of tin and copper in wetting and flow characteristics. BLF 227 is manufactured to exceed J-STD-006.

FEATURES

- Low cost, lead-free alloy
- Smooth solder joints with no visible shrinkage effects
- Excellent through-hole penetration and topside fillet
- Low dissolution of copper from boards and components into solder pot
- Near Eutectic alloy melting point of 227°C
- ROHS Complaint

FLUX COMPATIBILITY

BLF 227 alloy is compatible with many major electronic grade fluxes on the market today.

TEMPERATURE REQUIREMENTS

APPLICATION	RECOMMENDED TEMPERATURE
REFLOW SOLDERING	PEAK TEMPERATURE 210°-235°C (410°-455° F)
WAVE SOLDERING	POT TEMPERATURE OF 265°-280°C (520°-536°F)
HAND SOLDERING	TIP TEMPERATURE OF 370°-425°C (700°-800°)

AVAILABILITY

BLF 227 is available in bar, solid and cored wire, foil, spheres, preforms, ingot and anodes. Core wire fluxes include no clean, water soluble and rosin fluxes in diameters from .006 to .125 and flux percentages from 0.5% to 3.6%.



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